



Layer	Base CU / Plt	Thick	Type	Stackup	Subs	Imp	Material	Dk	Df
Silkscreen		0.00					Taiyo-SS - White		
Soldermask		0.60					Taiyo-SM - Green	2.70	0.033
Lyr1	0.5oz / Std	1.80	S						
Prepreg		7.94					370HR - 2x1080/1x106	3.82	0.025
Lyr2	1oz	1.20	P						
Core		39.00					370HR - 39.0mils	4.71	0.021
Lyr3	1oz	1.20	P						
Prepreg		7.94					370HR - 1x106/2x1080	3.82	0.025
Lyr4	0.5oz / Std	1.80	S						
Soldermask		0.60					Taiyo-SM - Green	2.70	0.033
Silkscreen		0.00					Taiyo-SS - White		

Required Thickness

Type	Req. Thick	Tol% +	Tol% -	Act. Thick	Measured
Overall	62.0	10.0	10.0	62.1	
Over lamination	58.4	10.0	10.0	58.5	
Over laminate	57.2	10.0	10.0	57.3	
Over metal	60.8	10.0	10.0	60.9	

Bill of Materials

Material	Qty/Panel	Total Qty
39.0mils 1/1 core	1	1
0.5oz foil	2	2
1080 prepreg	4	4
106 prepreg	2	2
White silkscreen	2	2
	11	11

Comments